Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D ** : Required Field*

Supplier Information			
Company Name *	**STMicroelectronics**	**Response Date ***	**2017-06-20**
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	**Representative Title**	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	**Representative Email ***	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard

Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not Verified

Digitally signed by rossana bonaccorso
Date: 2017.06.20 14:41:21 +02:00

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STN3P10F6	CSLL*6P02B6F	A	Z8GA	2017-06-20
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	110.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
1	210	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	6.5-3.5-1.8	4	gull wing	
Comment	Package: SOT 223			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	**true**
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false

Exemption Id.	**Description**
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			**Response**
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			**FALSE**
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			**TRUE**
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	die backside metal	91
Lead	1.97	soft solder	17936

QueryList : REACH-12th January 2017				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						**Mfr Item Name**	**CSLL*6P02B6F**					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	Other inorganic materials	1.386	mg	supplier	die	Silicon (Si)	7440-21-3		1.168	mg	842713	10618
				supplier	metallization	Aluminium (Al)	7429-90-5		0.188	mg	135642	1709
				supplier	Passivation	Silicon Oxide	7631-86-9		0.016	mg	11544	145
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.001	mg	722	9
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.010	mg	7215	91
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.003	mg	2165	27
Leadframe	Copper & its alloys	92.384	mg	supplier	alloy	Copper (Cu)	7440-50-8		91.802	mg	993700	834564
				supplier	alloy	CopperPosphorous (CuP)	12517-41-8		0.092	mg	996	836
				supplier	metallization	Silver (Ag)	7440-22-4		0.490	mg	5304	4455
Soft solder	Solder	2.066	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.973	mg	954985	17936
				supplier	solder	Silver (Ag)	7440-22-4		0.052	mg	25169	473
				supplier	solder	Tin (Sn)	7440-31-5		0.041	mg	19845	374
Bonding wires	Other inorganic materials	0.136	mg	supplier	wire	Copper (Cu)	7440-50-8		0.136	mg	1000000	1236
Encapsulation	Other Organic Materials	11.256	mg	supplier	mold compound	Silica, vitreous	60676-86-0		9.782	mg	869048	88927
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.900	mg	79957	8182
				supplier	mold compound	Phenol Resin	26834-02-6		0.451	mg	40068	4100
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.067	mg	5952	609
				supplier	mold compound	Carbon black	1333-86-4		0.056	mg	4975	509
Connections coating	Solder	2.772	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.772	mg	1000000	25200